



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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## Supplier Information

Company Name * STMicroelectronics	Company Unique ID	Unique ID Authority	Response Date * NA	Response Document ID				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *	Duplicate Contact -> Authorized Representative				
Authorized Representative * GIOVANNI GIACOPELLO	Title - Representative APM MD CHAMPION	Phone - Representative * NA	Email - Representative * NA	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
	TDA7492	D2KB*UQ30BB5	2011-03-09	A	MU1A	481.3	mg	Each
Alternate Recommendation	PowerSSO-36 slug up Package			Alternate Item Comments	ECOPACK2/ROHS BSA REF: CD00262790			

## Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Matte Tin (Sn) - annealed	CU Alloy	3	260 C	30 seconds	3

Comments

**DISCLAIMER: While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict "as is"**

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## RoHS Material Composition Declaration

Declaration Type \*

Simplified

RoHS Directive  
2002/95/EC

**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration \*

3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance \*

Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

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7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

## Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

+I	-I	Item/SubItem Name	+M	-M	Homogeneous Material	Weight	Unit of Measure	+C	-C	Level	Substance Category	+S	-S	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
																			-	+	
		D2KB*UQ30BB5			Silicon Die	6.714	mg			Supplier	Silicon die			Silicon	7440-21-3		6.665	mg			992,70
										Supplier	Die metallization			Copper (Cu)	7440-50-8		0.001	mg			149
														Chromium (Cr)	7440-47-3		0.004	mg			596
														Nickel (Ni)	7440-02-0		0.034	mg			5,064
														Gold (Au)	7440-57-5		0.01	mg			1,489
					Leadframe	225.487	mg			Supplier	Alloy			Copper (Cu)	7440-50-8		225.194	mg			998,70
														Iron (Fe)	7439-89-6		0.225	mg			998
														Iron Phosphide (FeP)	26508-33-8		0.068	mg			302
					Leadframe coating	2.028	mg			Supplier	Coating			Nickel (Ni)	7440-02-0		2.028	mg			1,000,0
					Die Attach	4.812	mg			JIG R	Lead/Lead Compound			Lead (Pb)	7439-92-1	7a. Lead	4.692	mg			975,06
										Supplier	Soft solder			Silver (Ag)	7440-22-4		0.072	mg			14,963
														Tin (Sn)	7440-31-5		0.048	mg			9,975
					Bonding wire	0.661	mg			Supplier	Bonding wire			Gold (Au)	7440-57-5		0.661	mg			1,000,0
					Encapsulation	233.627	mg			Supplier	Molding compound			Silica, vitreous	60676-86-0		209.797	mg			898,00
														Carbon-black	1333-86-4		0.467	mg			1,999
														epoxy resin	Proprietary		7.009	mg			30,001
														Phenol Resin	205830-20-2		9.345	mg			40,000
														Biphenyl epoxy resin	85954-11-6		7.009	mg			30,000
					Finishing	7.971	mg			Supplier	Connections coating			Tin (Sn)	7440-31-5		7.971	mg			1,000,0